PCN Number:	20221010002.1	PCN Date:	October 11, 2022
Title:	Qualification of new Fab site (FFAB) using qualified Process Technology, Die Revision, Datasheet update and additional Assembly BOM options for select devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Jan 11, 2023	Sample requests accepted until:	Nov 11, 2022*

*Sample requests received after November 11, 2022 will not be supported.

Change Type:

☐	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☒	Design	☒	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☒	Wafer Fab Materials	☒	Wafer Fab Process
		☐	Part number change		

Notification Details

Description of Change:

Texas Instruments is pleased to announce the qualification of a new fab & process technology (FFAB, BICOM3XHV) die revision, and Assembly BOM options for selected devices as listed below in the product affected section. Construction differences are noted below:

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
Semefab	D1-450	100 mm	FFAB	BICOM3XHV	200 mm

The die was also changed as a result of the process change.

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.

Changes from Revision B (April 2019) to Revision C (September 2022)   **Page**

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
INA118	SBOS027B	SBOS027C	http://www.ti.com/product/INA118

Additionally, there will be BOM options introduced for these devices as shown below:

	MLA Current	MLA Alternate
Wire type	1.2 mil Au	1.0mil Cu
Mount compound	4205846	4147858
Mold compound	4209640	4226323
Die Coat	4221706	No Die Coat
MSL level	3	2

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):
None
Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SEMFAB4	DISOL	USA	GLENROTHES
FFAB	**FRE**	**DEU**	**Freising**

Die Rev:

Current   **New**

Die Rev [2P]	**Die Rev [2P]**
A	**A**

Sample product shipping label (not actual product label)

Product Affected:

INA118U	INA118U/2K5G4	INA118UB/2K5	INA118UG4
INA118U/2K5	INA118UB	INA118UBG4	

Qualification Report
Approve Date 19-SEPTEMBER-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: INA118UB	QBS Process Reference: INA828ID	QBS Package Reference: INA849DR	QBS Product Reference: INA818ID
HAST	A2	Biased HAST	130C	96 Hours	-	3/231/0	-	-
HAST	A2	Temperature Humidity Bias	85C/85%RH	1000 Hours	-	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	-
HTOL	B1	Life Test	100C[B]	300 Hours	-	-	1/77/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	3/18/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	1/30/0	1/30/0

- QBS: Qual By Similarity
- Qual Device INA118UB is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2108-031

[B] Tj of device at 150C

For questions regarding this notice, e-mails can be sent to the contact below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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